

MATERIAL DECLARATION SHEET



Material	MF-PSML Series
Product Line	Multifuse
Revision Date	Oct. 12, 2014
Revision	A
RoHS Compliant	Yes
Halogen Free Compliant	Yes

No.	Breakdown of part (e.g. Lead, Ceramic body, coating, plating, additive)	Material/substance name (e.g. Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum (%)
1	Metal Carbide	Titanium Carbide	0.0030423	12070-08-5	44.261%	44.261%
2	Copper Plating	Copper	0.0004705	7440-50-8	6.845%	6.845%
3	Foil	Copper	0.0013714	7440-50-8	19.951%	21.001%
		Nickel	0.0000722	7440-02-0	1.050%	
4	PCB Foil	Copper	0.0008142	7440-50-8	11.846%	11.846%
5	Polymer	Polyethylene Homopolymer	0.0002387	9002-88-4	3.473%	3.478%
		Proprietary Additives	0.0000003	-	0.005%	
6	Prepreg	Epoxy	0.0005534	35948-25-5	8.051%	12.318%
		Glass fiber	0.0002933	65997-17-3	4.267%	
7	Soldering plating	Nickel	0.0000170	7440-02-0	0.248%	0.251%
		Gold	0.0000002	7440-57-5	0.003%	
		Total Weight (%)				

Total weight (grams)	0.0068735	Total	100%	100%
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